

# TLV0834C, TLV0834I, TLV0838C, TLV0838I

## 3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS

### WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

- 8-Bit Resolution
- 2.7-V to 3.6-V  $V_{CC}$
- Easy Microprocessor Interface or Stand-Alone Operation
- Operates Ratiometrically or With  $V_{CC}$  Reference
- 4- or 8-Channel Multiplexer Options With Address Logic
- Input Range 0 V to  $V_{CC}$  With  $V_{CC}$  Reference
- Remote Operation With Serial Data Link
- Inputs and Outputs Are Compatible With TTL and MOS
- Conversion Time of 32  $\mu$ s at  $f_{(CLK)} = 250$  kHz
- Functionally Equivalent to the ADC0834 and ADC0838 at 3-V Supply Without the Internal Zener Regulator Network
- Total Unadjusted Error . . .  $\pm 1$  LSB

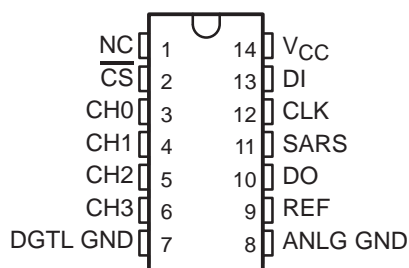
### description

These devices are 8-bit successive-approximation analog-to-digital converters, each with an input-configurable multichannel multiplexer and serial input/output. The serial input/output is configured to interface with standard shift registers or microprocessors. Detailed information on interfacing with most popular microprocessors is readily available from the factory.

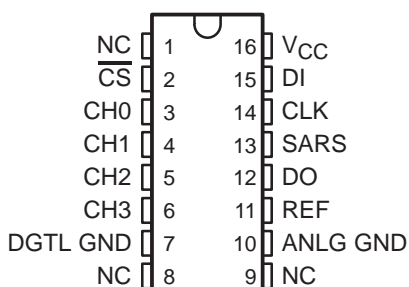
The TLV0834 (4-channel) and TLV0838 (8-channel) multiplexer is software-configured for single-ended or differential inputs as well as pseudodifferential input assignments. The differential analog voltage input allows for common-mode rejection or offset of the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding of any smaller analog voltage span to the full 8 bits of resolution.

The TLV0834C and TLV0838C are characterized for operation from 0°C to 70°C. The TLV0834I and TLV0838I are characterized for operation from –40°C to 85°C.

TLV0834 . . . D OR N PACKAGE  
(TOP VIEW)

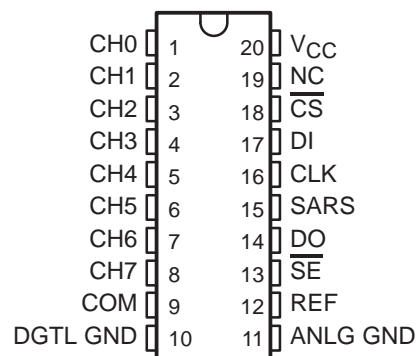


TLV0834 . . . PW PACKAGE  
(TOP VIEW)



NC – No internal connection

TLV0838 . . . PW, DW, OR N PACKAGE  
(TOP VIEW)



### AVAILABLE OPTIONS

T <sub>A</sub>	PACKAGE					
	SMALL OUTLINE (D)	SMALL OUTLINE (DW)	PLASTIC DIP (N)		TSSOP (PW)	
0°C to 70°C	TLV0834CD	TLV0838CDW	TLV0834CN	TLV0838CN	TLV0834CPW	TLV0838CPW
–40°C to 85°C	TLV0834ID	TLV0838IDW	TLV0834IN	TLV0838IN	TLV0834IPW	TLV0838IPW



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

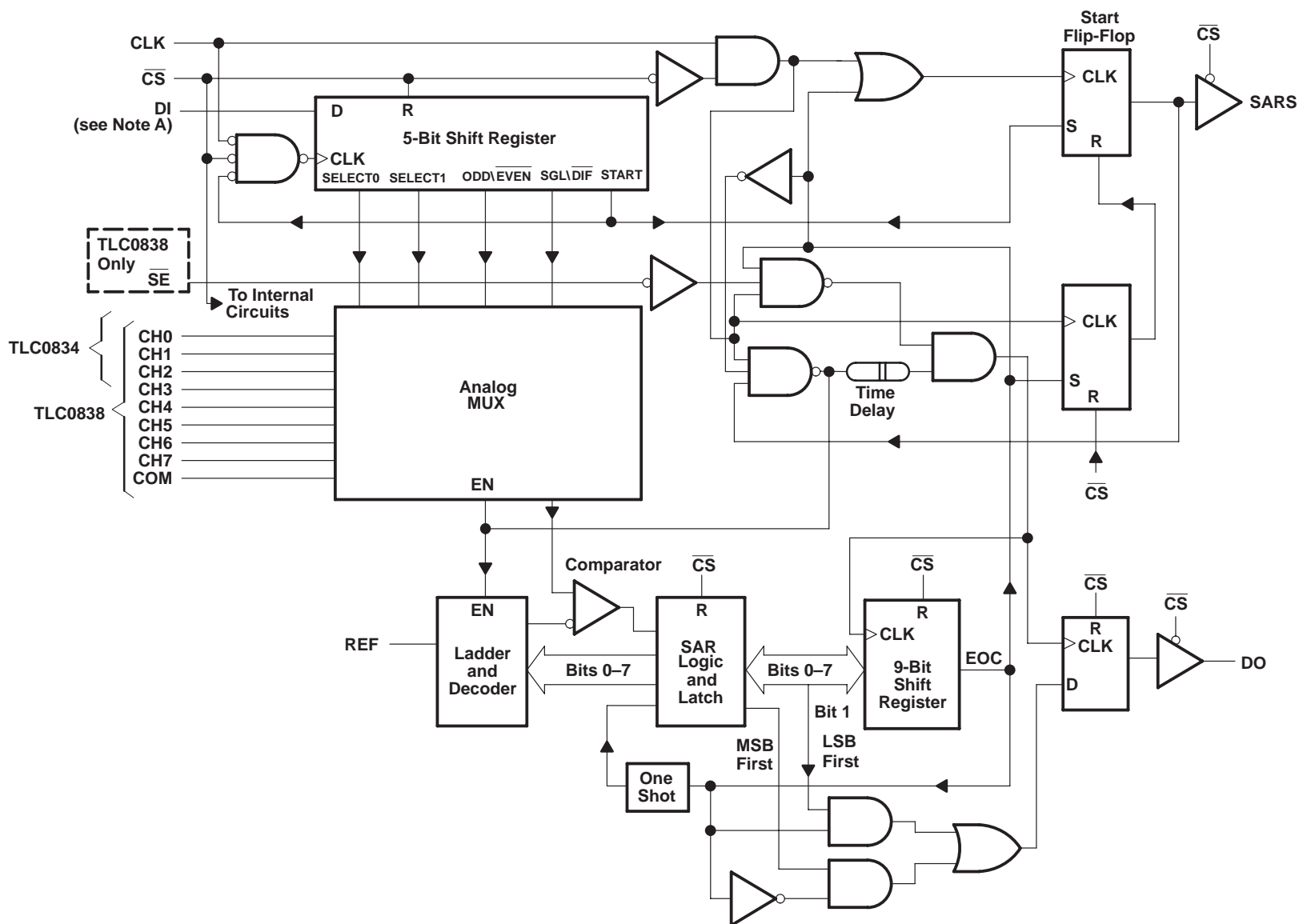
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2000, Texas Instruments Incorporated

## functional block diagram



NOTE A: For the TLC0834, DI is input directly to the D input of SELECT1; SELECT0 is forced to a high.

## functional description

The TLV0834 and TLV0838 use a sample-data-comparator structure that converts differential analog inputs by a successive-approximation routine. Operation of both devices is similar with the exception of  $\overline{SE}$ , an analog common input, and multiplexer addressing. The input voltage to be converted is applied to a channel terminal and is compared to ground (single ended), to an adjacent input (differential), or to a common terminal (pseudo differential) that can be an arbitrary voltage. The input terminals are assigned a positive (+) or negative (–) polarity. When the signal input applied to the assigned positive terminal is less than the signal on the negative terminal, the converter output is all zeros.

Channel selection and input configuration are under software control using a serial-data link from the controlling processor. A serial-communication format allows more functions to be included in a converter package with no increase in size. In addition, it eliminates the transmission of low-level analog signals by locating the converter at the analog sensor and communicating serially with the controlling processor. This process returns noise-free digital data to the processor.

A particular input configuration is assigned during the multiplexer-addressing sequence. The multiplexer address shifts into the converter through the data input (DI) line. The multiplexer address selects the analog inputs to be enabled and determines whether the input is single ended or differential. When the input is differential, the polarity of the channel input is assigned. Differential inputs are assigned to adjacent channel pairs. For example, channel 0 and channel 1 may be selected as a differential pair. These channels cannot act differentially with any other channel. In addition to selecting the differential mode, the polarity may also be selected. Either channel of the channel pair may be designated as the negative or positive input.

The common input on the TLV0838 can be used for a pseudodifferential input. In this mode, the voltage on the common input is considered to be the negative differential input for all channel inputs. This voltage can be any reference potential common to all channel inputs. Each channel input can then be selected as the positive differential input. This feature is useful when all analog circuits are biased to a potential other than ground.

A conversion is initiated by setting  $\overline{CS}$  low, which enables all logic circuits.  $\overline{CS}$  must be held low for the complete conversion process. A clock input is then received from the processor. On each low-to-high transition of the clock input, the data on DI is clocked into the multiplexer-address shift register. The first logic high on the input is the start bit. A 3- to 4-bit assignment word follows the start bit. On each successive low-to-high transition of the clock input, the start bit and assignment word are shifted through the shift register. When the start bit is shifted into the start location of the multiplexer register, the input channel is selected and conversion starts. The SAR status output (SARS) goes high to indicate that a conversion is in progress, and DI to the multiplexer shift register is disabled for the duration of the conversion.

An interval of one clock period is automatically inserted to allow the selected multiplexed channel to settle. DO comes out of the high-impedance state and provides a leading low for one clock period of multiplexer settling time. The SAR comparator compares successive outputs from the resistive ladder with the incoming analog signal. The comparator output indicates whether the analog input is greater than or less than the resistive-ladder output. As the conversion proceeds, conversion data is simultaneously output from DO, with the most significant bit (MSB) first. After eight clock periods, the conversion is complete and SARS goes low.

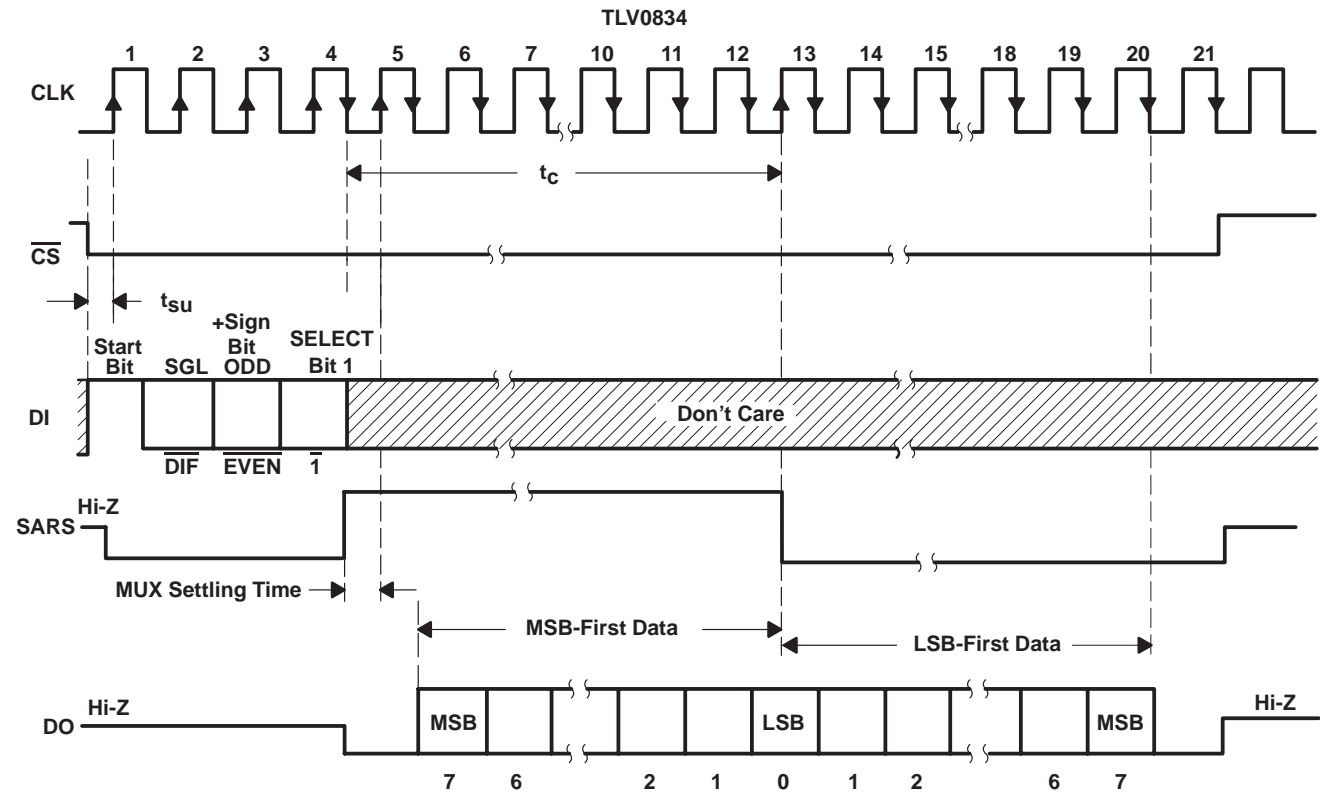
The TLV0834 outputs the least-significant-bit (LSB) first data after the MSB-first data stream. When  $\overline{SE}$  is held high on the TLV0838, the value of the LSB remains on the data line. When  $\overline{SE}$  is forced low, the data is then clocked out as LSB-first data. (To output LSB first,  $\overline{SE}$  must first go low, then the data stored in the 9-bit shift register outputs LSB first.) When  $\overline{CS}$  goes high, all internal registers are cleared. At this time, the output circuits go to the high-impedance state. If another conversion is desired,  $\overline{CS}$  must make a high-to-low transition followed by address information.

DI and DO can be tied together and controlled by a bidirectional processor I/O bit received on a single wire. This is possible because DI is only examined during the multiplexer-addressing interval and DO is still in the high-impedance state.

# TLV0834C, TLV0834I, TLV0838C, TLV0838I 3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

## sequence of operation



TLV0834 MUX-ADDRESS CONTROL LOGIC TABLE

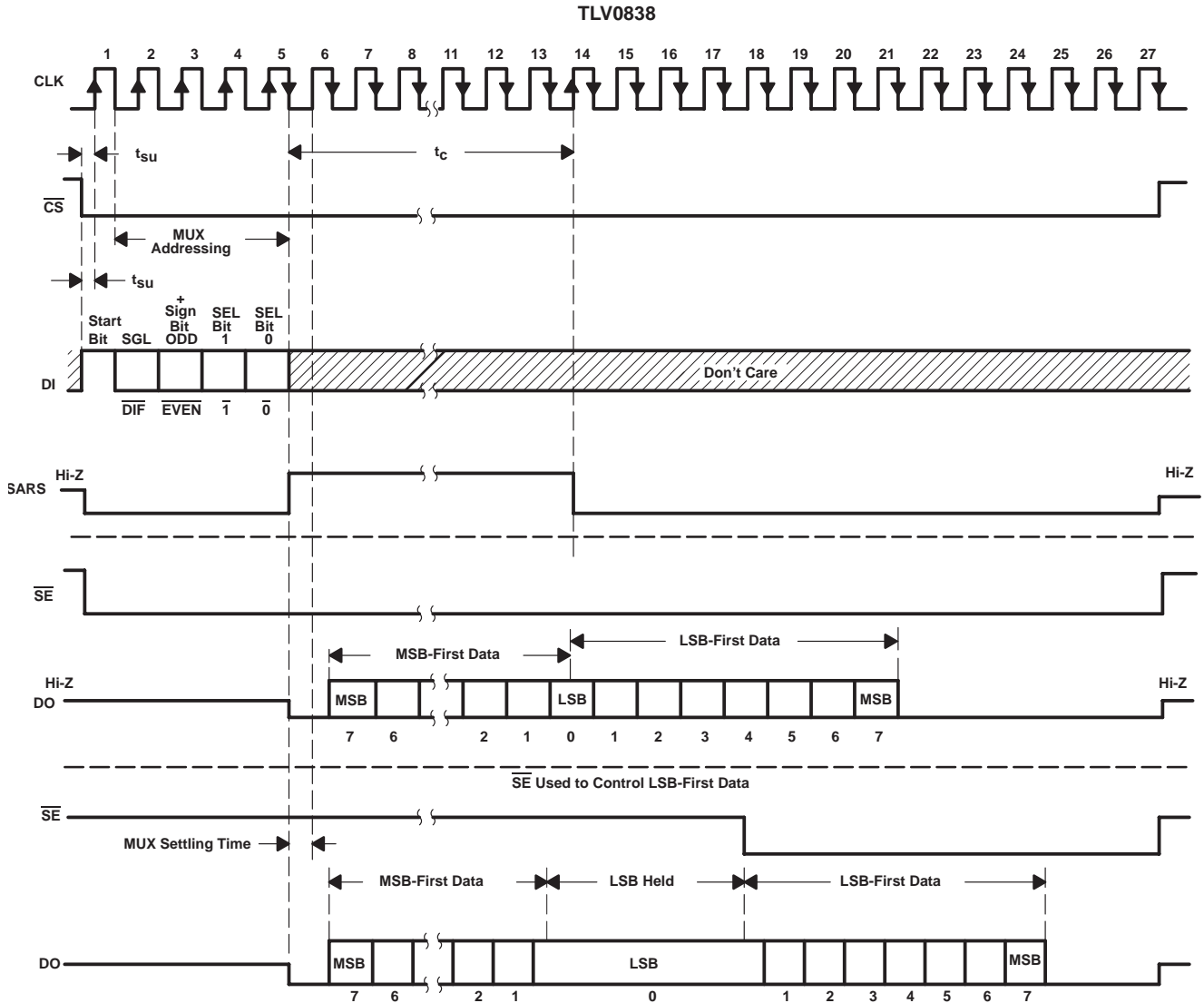
MUX ADDRESS			CHANNEL NUMBER			
SGL/ $\overline{\text{DIF}}$	ODD/ $\overline{\text{EVEN}}$	SELECT BIT 1	CH0	CH1	CH2	CH3
L	L	L	+	-		
L	L	H			+	-
L	H	L	-	+		
L	H	H			-	+
H	L	L	+			
H	L	H			+	
H	H	L		+		
H	H	H				+

H = high level, L = low level, - or + = terminal polarity for the selected input channel

TLV0834C, TLV0834I, TLV0838C, TLV0838I  
3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS  
WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

sequence of operation (continued)



**TLV0834C, TLV0834I, TLV0838C, TLV0838I**

## 3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS

## WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

### TLV0838 MUX-ADDRESS CONTROL LOGIC TABLE

MUX ADDRESS				SELECTED CHANNEL NUMBER								COM	
SGL/DIF	ODD/EVEN	SELECT		0		1		2		3			
		1	0	CH0	CH1	CH2	CH3	CH4	CH5	CH6	CH7		
L	L	L	L	+	-								
L	L	L	H			+	-						
L	L	H	L					+	-				
L	L	H	H							+	-		
L	H	L	L	-	+								
L	H	L	H			-	+						
L	H	H	L					-	+				
L	H	H	H							-	+		
H	L	L	L	+									-
H	L	L	H			+							-
H	L	H	L					+					-
H	L	H	H							+			-
H	H	L	L		+								-
H	H	L	H				+						-
H	H	H	L						+				-
H	H	H	H								+		-

H = high level, L = low level, - or + = polarity of external input

absolute maximum ratings over recommended operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC}$ (see Note 1)	6.5 V
Input voltage range: Logic	-0.3 V to $V_{CC} + 0.3$ V
Analog	-0.3 V to $V_{CC} + 0.3$ V
Input current, $I_I$	$\pm 5$ mA
Total input current	$\pm 20$ mA
Operating free-air temperature range, $T_A$ : C suffix	0°C to 70°C
I suffix	-40°C to 85°C
Storage temperature range, $T_{stg}$	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to the network ground terminal.

**TLV0834C, TLV0834I, TLV0838C, TLV0838I**  
**3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS**  
**WITH SERIAL CONTROL**

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

**recommended operating conditions**

		MIN	NOM	MAX	UNIT
Supply voltage, $V_{CC}$ (see clock frequency operating conditions)		2.7	3.3	3.6	V
High-level input voltage, $V_{IH}$		2			V
Low-level input voltage, $V_{IL}$				0.8	V
Clock frequency, $f_{(CLK)}$	$V_{CC} = 2.7\text{ V}$	10		250	kHz
Clock frequency, $f_{(CLK)}$	$V_{CC} = 3.3\text{ V}$	10		600	kHz
Clock duty cycle (see Note 2)		40%		60%	
Pulse duration, $\overline{CS}$ high, $t_w$		220			ns
Setup time, $\overline{CS}$ low, $\overline{SE}$ low, or data valid before $CLK\uparrow$ , $t_{su}$		350			ns
Hold time, data valid after $CLK\uparrow$ , $t_h$		90			ns
Operating free-air temperature, $T_A$	C suffix	0		70	°C
	I suffix	–40		85	

NOTE 2: The clock-duty-cycle range ensures proper operation at all clock frequencies. When a clock frequency is used outside the recommended duty-cycle range, the minimum pulse duration (high or low) is 1  $\mu$ s.

**electrical characteristics over recommended range of operating free-air temperature,  $V_{CC} = 3.3\text{ V}$ ,  $f_{(CLK)} = 250\text{ kHz}$  (unless otherwise noted)**

**digital section**

PARAMETER	TEST CONDITIONS†	C SUFFIX			I SUFFIX			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{OH}$ High-level output voltage	$V_{CC} = 3\text{ V}$ , $I_{OH} = -360\text{ }\mu\text{A}$	2.8			2.4			V
	$V_{CC} = 3\text{ V}$ , $I_{OH} = -10\text{ }\mu\text{A}$	2.9			2.8			
$V_{OL}$ Low-level output voltage	$V_{CC} = 3\text{ V}$ , $I_{OL} = 1.6\text{ mA}$			0.34			0.4	V
$I_{IH}$ High-level input current	$V_{IH} = 3.6\text{ V}$		0.005	1		0.005	1	$\mu\text{A}$
$I_{IL}$ Low-level input current	$V_{IL} = 0$		–0.005	–1		–0.005	–1	$\mu\text{A}$
$I_{OH}$ High-level output (source) current	At $V_{OH}$ , $DO = 0\text{ V}$ , $T_A = 25^\circ\text{C}$	–6.5	–15		–6.5	–15		mA
$I_{OL}$ Low-level output (sink) current	At $V_{OL}$ , $DO = V_{CC}$ , $T_A = 25^\circ\text{C}$	8	16		8	16		mA
$I_{OZ}$ High-impedance-state output current (DO or SARS)	$V_O = 3.3\text{ V}$ , $T_A = 25^\circ\text{C}$		0.01	3		0.01	3	$\mu\text{A}$
	$V_O = 0$ , $T_A = 25^\circ\text{C}$		–0.01	–3		–0.01	–3	
$C_i$ Input capacitance						5		pF
$C_o$ Output capacitance						5		pF

† All parameters are measured under open-loop conditions with zero common-mode input voltage (unless otherwise specified).

‡ All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

# TLV0834C, TLV0834I, TLV0838C, TLV0838I

## 3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS

### WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

**electrical characteristics over recommended range of operating free-air temperature,  $V_{CC} = 3.3\text{ V}$ ,  $f_{(CLK)} = 250\text{ kHz}$  (unless otherwise noted) (continued)**

#### analog and converter section

PARAMETER		TEST CONDITION <sup>†</sup>	MIN	TYP <sup>‡</sup>	MAX	UNIT
$V_{IC}$	Common-mode input voltage	See Note 3	–0.05 to $V_{CC}+0.05$			V
$I_{I(stdb)}$	Standby input current (see Note 4)	On channel	$V_I = 3.3\text{ V}$		1	$\mu\text{A}$
		Off channel	$V_I = 0$		–1	
		On channel	$V_I = 0$		–1	
		Off channel	$V_I = 3.3\text{ V}$		1	
$r_{i(REF)}$	Input resistance to REF		1.3	2.4	5.9	$\text{k}\Omega$

#### total device

PARAMETER		MIN	TYP <sup>‡</sup>	MAX	UNIT
$I_{CC}$	Supply current		0.2	0.75	mA

<sup>†</sup> All parameters are measured under open-loop conditions with zero common-mode input voltage.

<sup>‡</sup> All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

NOTES: 3. When channel IN– is more positive than channel IN+, the digital output code is 0000 0000. Connected to each analog input are two on-chip diodes that conduct forward current for analog input voltages one diode drop above  $V_{CC}$ . Care must be taken during testing at low  $V_{CC}$  levels (3 V) because high-level analog input voltage (3.6 V) can, especially at high temperatures, cause the input diode to conduct and cause errors for analog inputs that are near full scale. As long as the analog voltage does not exceed the supply voltage by more than 50 mV, the output code is correct. To achieve an absolute 0- to 3.3-V input range requires a minimum  $V_{CC}$  of 3.25 V for all variations of temperature and load.

4. Standby input currents go in or out of the on or off channels when the A/D converter is not performing conversion and the clock is in a high or low steady-state condition.

**operating characteristics,  $V_{CC} = 3.3\text{ V}$ ,  $f_{(CLK)} = 250\text{ kHz}$ ,  $t_r = t_f = 20\text{ ns}$ ,  $T_A = 25^\circ\text{C}$  (unless otherwise noted)**

PARAMETER		TEST CONDITIONS <sup>§</sup>	MIN	TYP	MAX	UNIT
Supply-voltage variation error		$V_{CC} = 3\text{ V to }3.6\text{ V}$	$\pm 1/16$	$\pm 1/4$		LSB
Total unadjusted error (see Note 5)		$V_{ref} = 3.3\text{ V}$ , $T_A = \text{MIN to MAX}$		$\pm 1$		LSB
Common-mode error		Differential mode	$\pm 1/16$	$\pm 1/4$		LSB
$t_{pd}$	Propagation delay time, output data after CLK↓ (see Note 6)	$C_L = 100\text{ pF}$			500	ns
					200	
$t_{dis}$	Output disable time, DO or SARS after CS↑	$C_L = 10\text{ pF}$ , $R_L = 10\text{ k}\Omega$			80	ns
		$C_L = 100\text{ pF}$ , $R_L = 2\text{ k}\Omega$			250	
$t_c$	Conversion time (multiplexer-addressing time not included)				8	clock periods

<sup>§</sup> All parameters are measured under open-loop conditions with zero common-mode input voltage. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Total unadjusted error includes offset, full-scale, linearity, and multiplexer errors.

6. The MSB-first data is output directly from the comparator and, therefore, requires additional delay to allow for comparator response time.





## PARAMETER MEASUREMENT INFORMATION

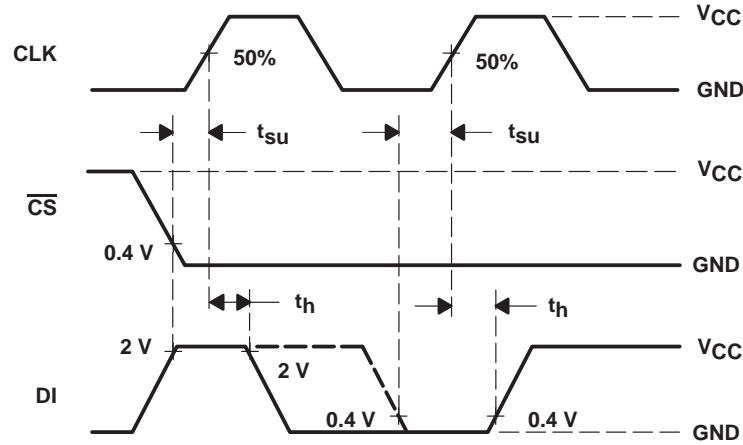


Figure 1. Data-Input Timing

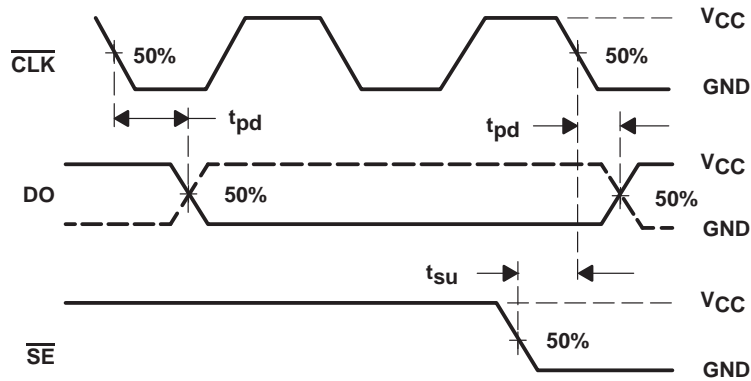


Figure 2. Data-Output Timing

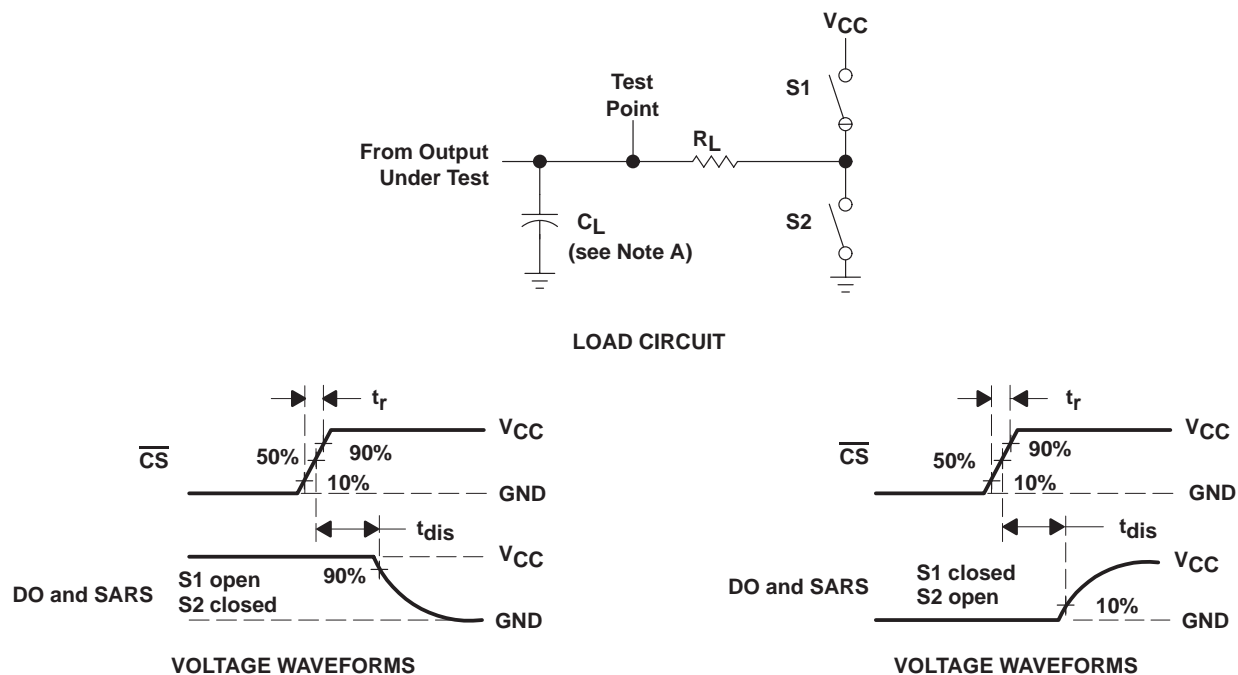
# TLV0834C, TLV0834I, TLV0838C, TLV0838I

## 3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS

### WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

#### PARAMETER MEASUREMENT INFORMATION



NOTE A:  $C_L$  includes probe and jig capacitance.

Figure 3. Output Disable Time Test Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS

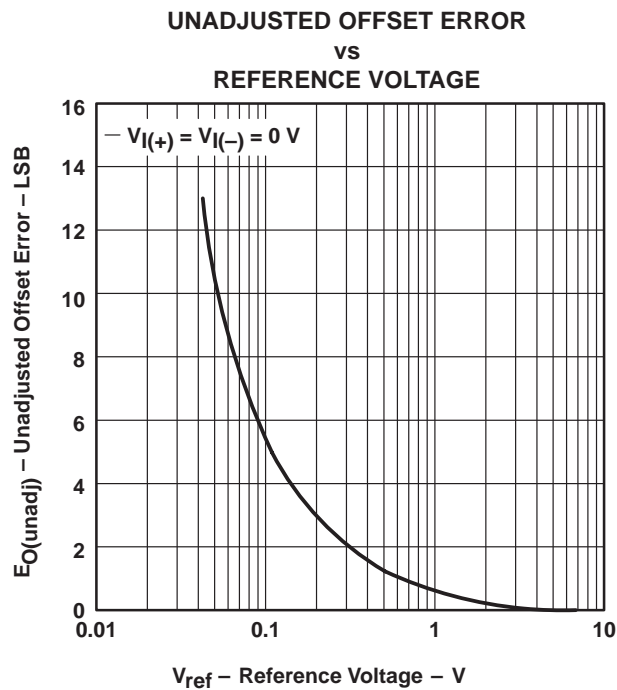


Figure 4

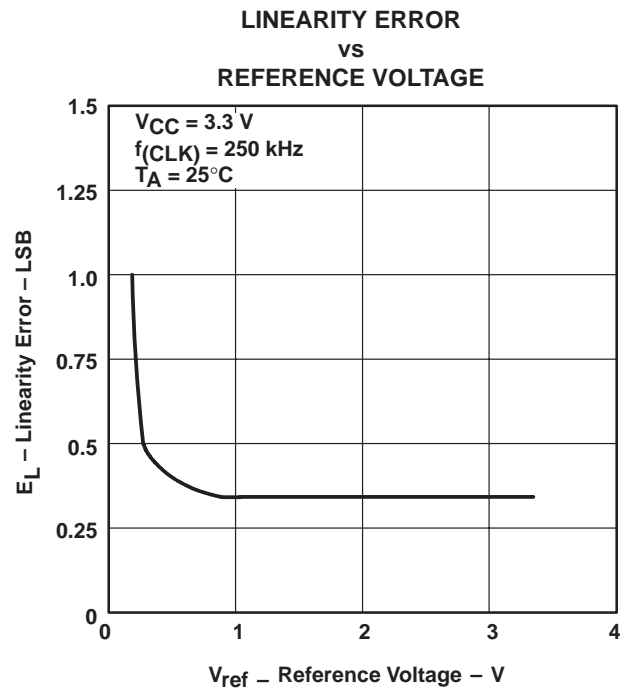


Figure 5

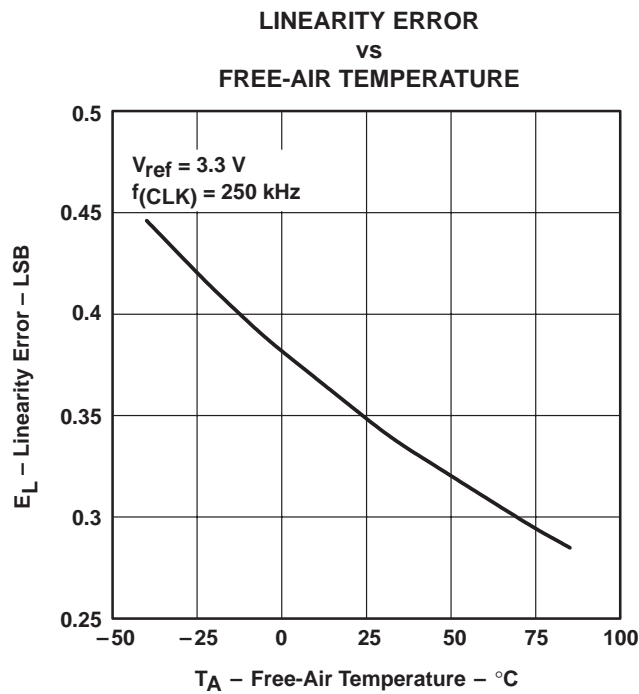


Figure 6

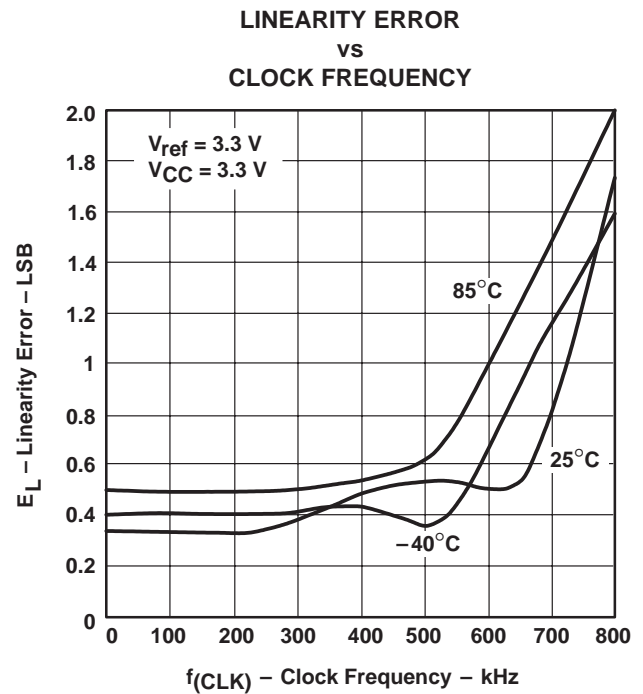


Figure 7

# TLV0834C, TLV0834I, TLV0838C, TLV0838I

## 3-VOLT 8-BIT ANALOG-TO-DIGITAL CONVERTERS

### WITH SERIAL CONTROL

SLAS147B – SEPTEMBER 1996 – REVISED OCTOBER 2000

#### TYPICAL CHARACTERISTICS

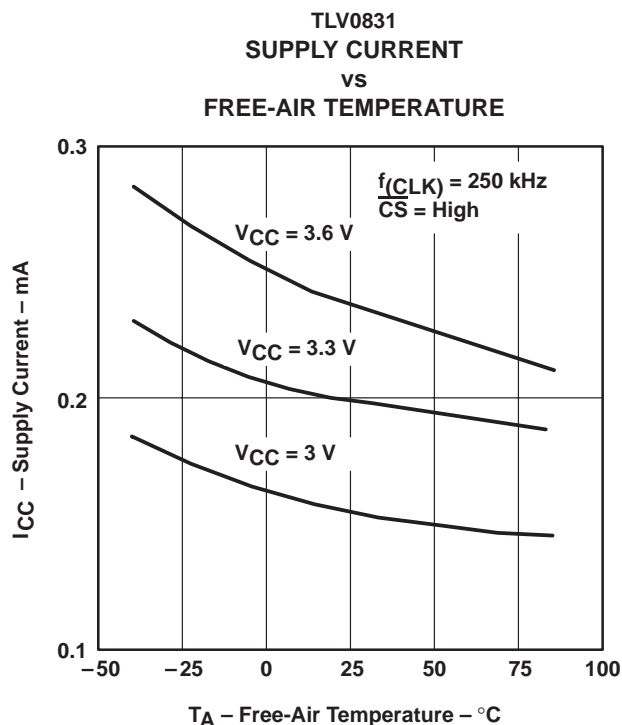


Figure 8

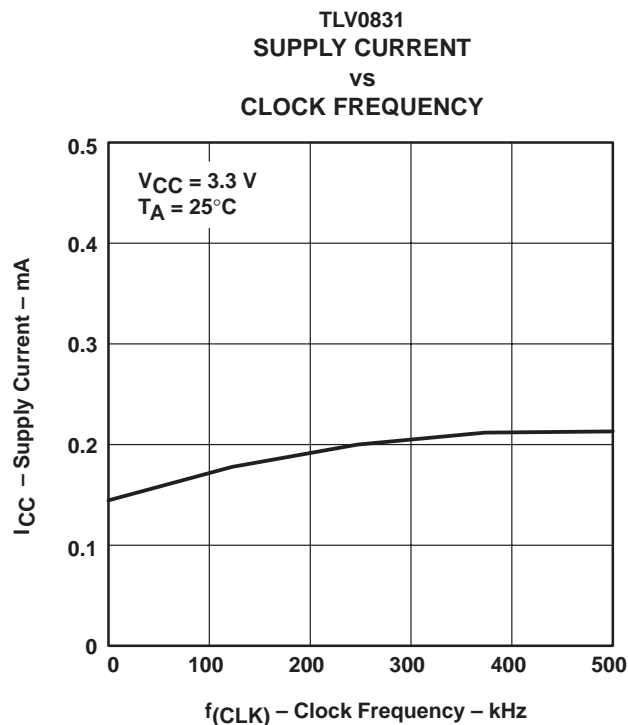


Figure 9

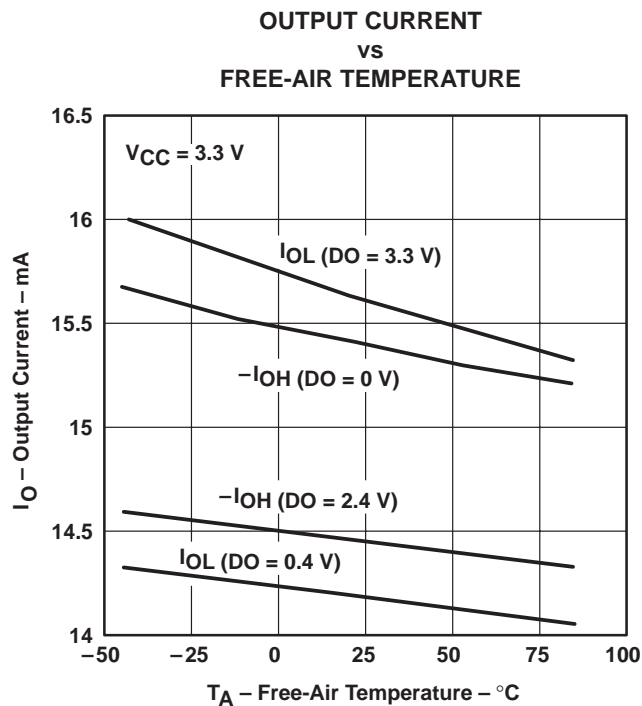


Figure 10

## TYPICAL CHARACTERISTICS

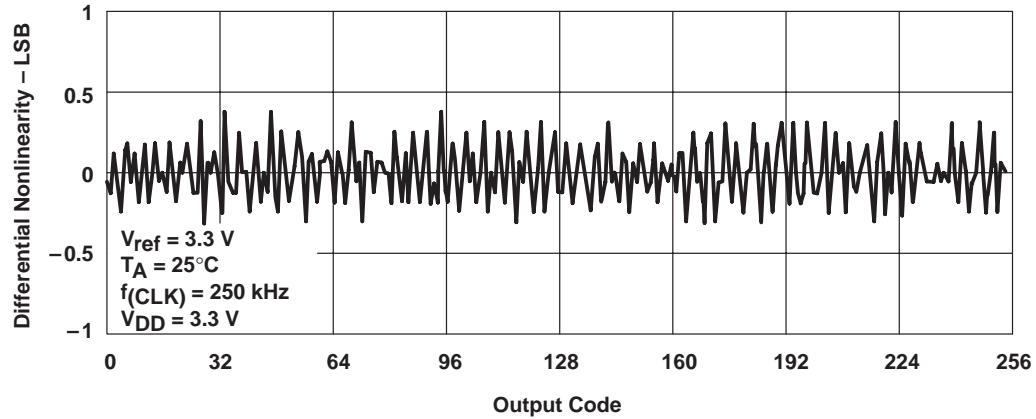


Figure 11. Differential Nonlinearity With Output Code

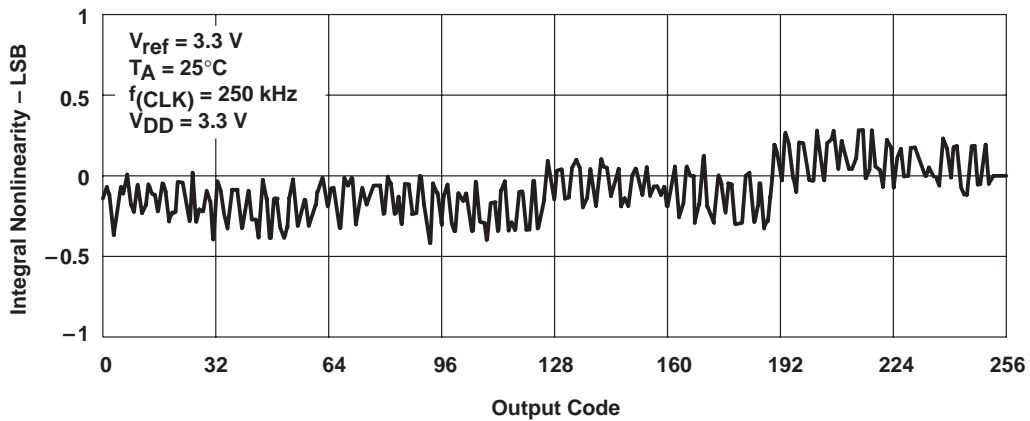


Figure 12. Integral Nonlinearity With Output Code

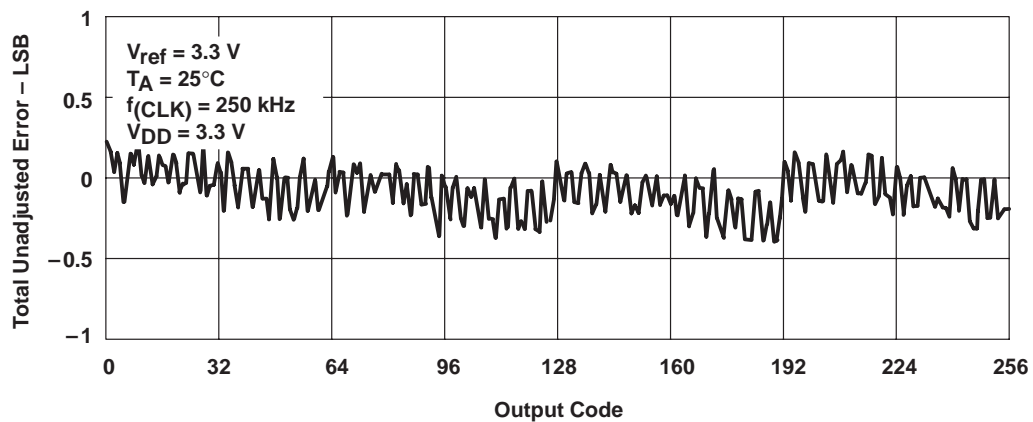


Figure 13. Total Unadjusted Error With Output Code

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLV0834CD</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0834C
TLV0834CD.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0834C
<a href="#">TLV0834CDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0834C
TLV0834CDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0834C
<a href="#">TLV0834CPW</a>	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV0834
TLV0834CPW.A	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TV0834
<a href="#">TLV0834CPWR</a>	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TV0834
TLV0834CPWR.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TV0834
<a href="#">TLV0834ID</a>	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0834I
TLV0834ID.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0834I
<a href="#">TLV0834IDR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0834I
TLV0834IDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0834I
<a href="#">TLV0834IN</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-	TLV0834IN
TLV0834IN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TLV0834IN
<a href="#">TLV0834IPW</a>	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY0834
TLV0834IPW.A	Active	Production	TSSOP (PW)   16	90   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY0834
<a href="#">TLV0834IPWR</a>	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY0834
TLV0834IPWR.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY0834
TLV0834IPWRG4	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TY0834
<a href="#">TLV0838CDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0838C
TLV0838CDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838C
<a href="#">TLV0838CDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0838C
TLV0838CDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838C
<a href="#">TLV0838CN</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-	TLV0838CN
TLV0838CN.A	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	TLV0838CN
<a href="#">TLV0838CPW</a>	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV0838C
TLV0838CPW.A	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838C
<a href="#">TLV0838CPWR</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TLV0838C
TLV0838CPWR.A	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838C

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TLV0838IDW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0838I
TLV0838IDW.A	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838I
<a href="#">TLV0838IDWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	TLV0838I
TLV0838IDWR.A	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838I
<a href="#">TLV0838IPW</a>	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838I
TLV0838IPW.A	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838I
<a href="#">TLV0838IPWR</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838I
TLV0838IPWR.A	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TLV0838I

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV0834CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV0834CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV0834IDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
TLV0834IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TLV0838CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLV0838CPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
TLV0838IDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
TLV0838IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

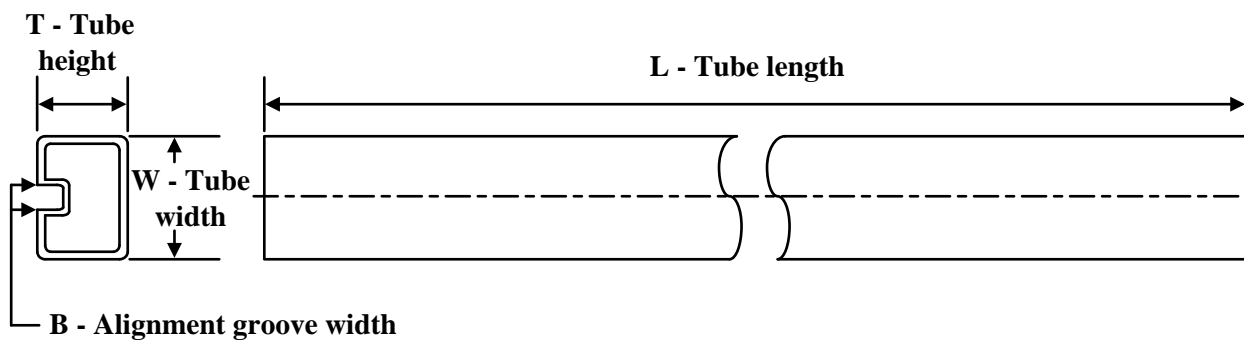
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLV0834CDR	SOIC	D	14	2500	350.0	350.0	43.0
TLV0834CPWR	TSSOP	PW	16	2000	350.0	350.0	43.0
TLV0834IDR	SOIC	D	14	2500	350.0	350.0	43.0
TLV0834IPWR	TSSOP	PW	16	2000	350.0	350.0	43.0
TLV0838CDWR	SOIC	DW	20	2000	350.0	350.0	43.0
TLV0838CPWR	TSSOP	PW	20	2000	350.0	350.0	43.0
TLV0838IDWR	SOIC	DW	20	2000	350.0	350.0	43.0
TLV0838IPWR	TSSOP	PW	20	2000	350.0	350.0	43.0

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TLV0834CD	D	SOIC	14	50	505.46	6.76	3810	4
TLV0834CD.A	D	SOIC	14	50	505.46	6.76	3810	4
TLV0834CPW	PW	TSSOP	16	90	530	10.2	3600	3.5
TLV0834CPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5
TLV0834ID	D	SOIC	14	50	505.46	6.76	3810	4
TLV0834ID.A	D	SOIC	14	50	505.46	6.76	3810	4
TLV0834IN	N	PDIP	14	25	506	13.97	11230	4.32
TLV0834IN.A	N	PDIP	14	25	506	13.97	11230	4.32
TLV0834IPW	PW	TSSOP	16	90	530	10.2	3600	3.5
TLV0834IPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5
TLV0838CDW	DW	SOIC	20	25	506.98	12.7	4826	6.6
TLV0838CDW.A	DW	SOIC	20	25	506.98	12.7	4826	6.6
TLV0838CN	N	PDIP	20	20	506	13.97	11230	4.32
TLV0838CN.A	N	PDIP	20	20	506	13.97	11230	4.32
TLV0838CPW	PW	TSSOP	20	70	530	10.2	3600	3.5
TLV0838CPW.A	PW	TSSOP	20	70	530	10.2	3600	3.5
TLV0838IDW	DW	SOIC	20	25	506.98	12.7	4826	6.6
TLV0838IDW.A	DW	SOIC	20	25	506.98	12.7	4826	6.6
TLV0838IPW	PW	TSSOP	20	70	530	10.2	3600	3.5
TLV0838IPW.A	PW	TSSOP	20	70	530	10.2	3600	3.5



## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

**D0014A****PACKAGE OUTLINE****SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4220204/A 02/2017

## NOTES:

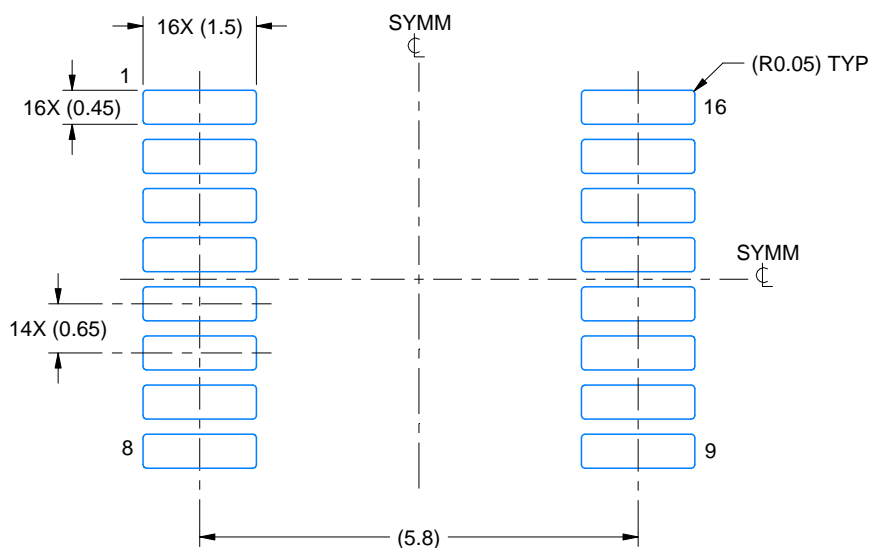
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

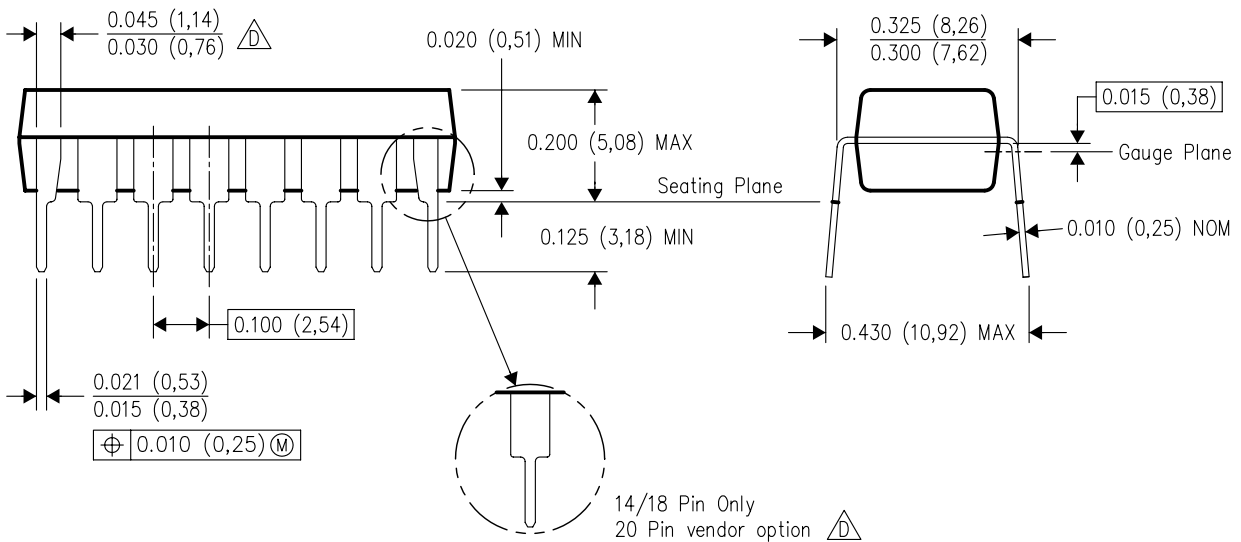
## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

## NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2025, Texas Instruments Incorporated